

board, via said through hole.

2. (Amended) The radiator mechanism according to claim 1, wherein at least a portion of the heat pipe runs parallel to the front surface and to the back surface.

3. (Amended) The radiator mechanism according to claim 1, [wherein the] further comprising a heat sink that comprises a cooling fin mounted on the front surface of the circuit board and a cooling fan disposed above the through hole.

4. (Amended) The radiator mechanism according to claim 3, wherein the cooling fan rotates around an axis perpendicular to said front surface of said circuit board, and absorbs air from said back surface of said circuit board.

5. (Amended) The radiator mechanism according to claim 4, wherein the cooling fan exhausts the air in a direction parallel to said front surface of said circuit board, whereby the air flows over said heat sink.

6. (Amended) The radiator mechanism according to claim 5, wherein the cooling fan and the heat sink are comprised in a fan-cum-heat sink unit.

7. (Amended) The radiator mechanism according to claim 5, wherein at least a portion

*CyB*  
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of the heat pipe runs parallel to the front surface and to the back surface.

Add the following new claims 8-9.

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*D.P. Sub C1*  
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*ADD*  
*BK*
8. (Added) A radiator mechanism comprising:  
a printed circuit board, including a through hole;  
a ventilation fan rotating around a rotation axis intersecting the printed circuit board at said through hole;  
a housing wall standing from a surface of the printed circuit board at a periphery of the ventilation fan; and  
an outlet defined in the housing wall,  
wherein said ventilation fan is held by said housing.
9. (Added) The radiator mechanism according to claim 8, wherein the ventilation fan is a centrifugal fan.